

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp = 8/20μs)	P _{pk}	200	Watts
Peak Pulse Current (tp = 8/20µs)	I _{PP}	4	А
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	25 15	kV
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C

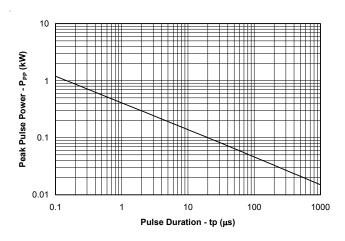
Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2			24	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2	26.7			V
Reverse Leakage Current	I _R	V _{RWM} = 24V, T=25°C Pin 1 or Pin 2 to Pin 3 and Between Pins 1 and 2			1	μΑ
Clamping Voltage	V _c	I _{pp} = 1A, tp = 8/20μs Pin 1 to Pin 2			45	V
Clamping Voltage	V _c	I _{pp} = 4A, tp = 8/20μs Pin 1 or Pin 2 to Pin 3			50	V
Clamping Voltage	V _c	I _{pp} = 4A, tp = 8/20μs Pin 1 to Pin 2			55	V
Junction Capacitance	C _j	V _R = OV, f = 1MHz Pin 1 to Pin 2		0.60	0.9	pF
Junction Capacitance	C _j	V _R = 0V, f = 1MHz Pin 1 or Pin 2 to Pin 3			1.5	pF

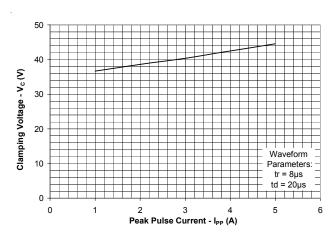


Typical Characteristics

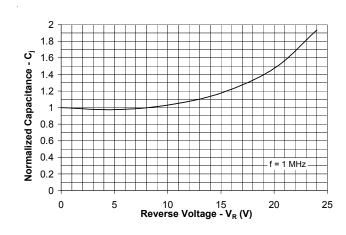
Non-Repetitive Peak Pulse Power vs. Pulse Time



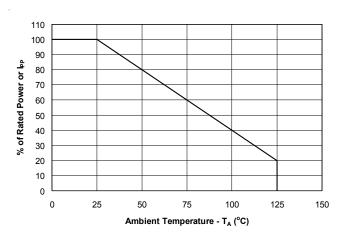
Clamping Voltage vs. Peak Pulse Current Pin 1 to Pin 2



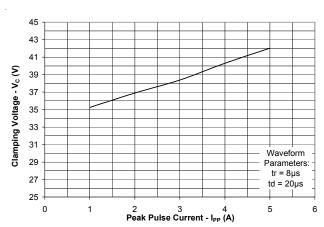
Normalized Capacitance vs. Reverse Voltage Pin 1 or Pin 2 to Pin 3



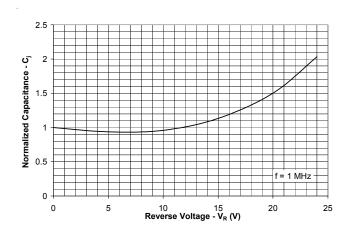
Power Derating Curve



Clamping Voltage vs. Peak Pulse Current Pin 1 or Pin 2 to Pin 3



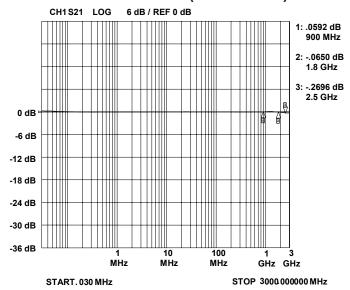
Normalized Capacitance vs. Reverse Voltage Pin 1 to Pin 2



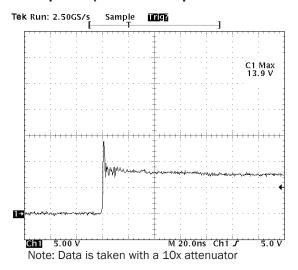


Typical Characteristics

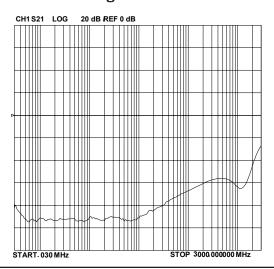
Insertion Loss S21 (Pin 1 to Pin 2)



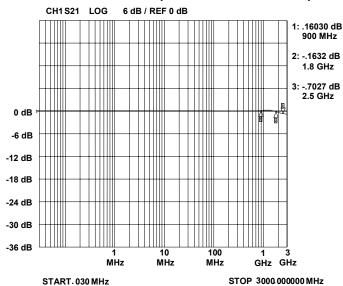
ESD Response (4kV Contact per IEC 61000-4-2)



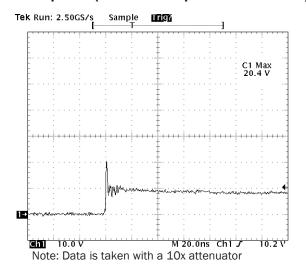
Analog Crosstalk



Insertion Loss S21 (Pin 1 or Pin 2 to Pin 3)



ESD Response (8kV Contact per IEC 61000-4-2)





Applications Information

Device Connection Options

This device is optimized for protection of 1 line operating in excess of 3GHz. It may also be used to protect two lines operating in excess of 2.0GHz. The device is connected as follows:

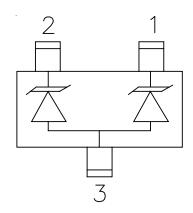
Protection for one line with <1pF capacitance can be achieved by connecting one data line to either pin 1 or pin 2 with the other pin connected to ground. Pin 3 is not connected. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

Protection of two lines is achieved by connecting data lines at pins 1 & 2. Pin 3 is connected to ground. The connection to ground should be made directly to a ground plane. The path length should also be kept as short as possible to minimize parasitic inductance.

Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

Figure 1. Pin Configuration





Applications Information - Spice Model

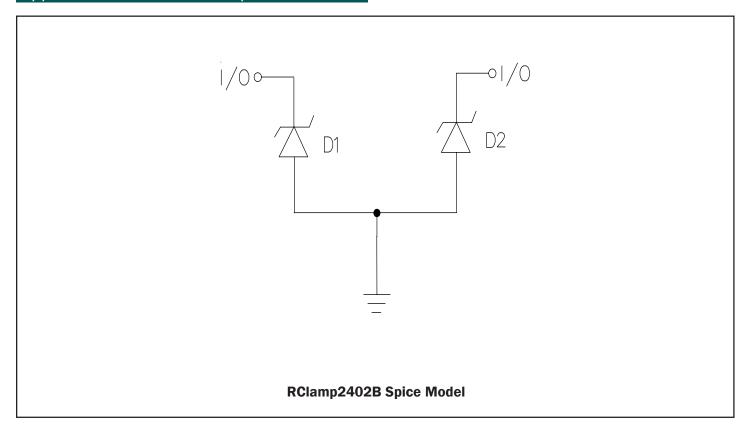
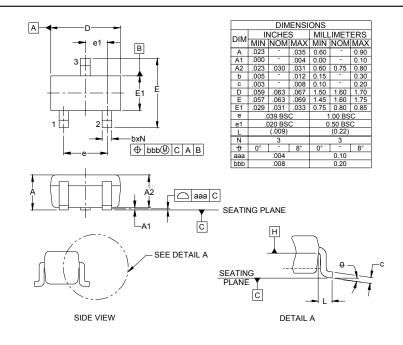


Table 1 - RClamp2402B Spice Parameters							
Parameter	Unit	D1 (TVS)	D2 (TVS)				
IS	Amp	1.93E-14	1.93E-14				
BV	Volt	32.4	32.4				
٧J	Volt	0.68	0.68				
RS	Ohm	2.04	2.04				
IBV	Amp	1.0E-3	1.0E-3				
CJO	Farad	0.73E-12	0.73E-12				
TT	sec	2.541E-9	2.541E-9				
M		0.412	0.412				
N		1.1	1.1				
EG	eV	1.11	1.11				



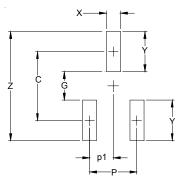
Outline Drawing -SC-75 (SOT-523)



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-
- 3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

Land Pattern -SC-75 (SOT-523)



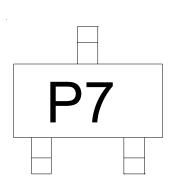
DIMENSIONS						
DIM	INCHES MILLIMETE					
С	(.055)	(1.40)				
Р	.039	1.00				
p1	.020	0.50				
G	.024	0.60				
Х	.016	0.40				
Υ	.031	0.80				
Ζ	.087	2.20				

NOTES:

 THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.



Marking

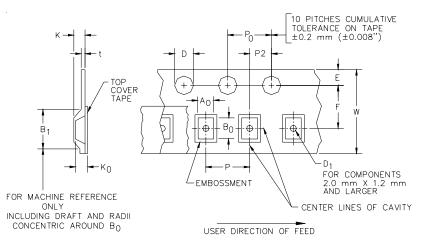


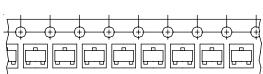
Ordering Information

Part Number	Lead	Qty per	Reel	
	Finish	Reel	Size	
RClamp2402B.TCT	Pb Free	3,000	7 Inch	

RailClamp and RClamp are registered marks of Semtech Corporation

Tape and Reel Specification





Device Orientation in Tape

Tape Width	B, (Max)	D	D1 (MIN)	E	F	K (MAX)	Р	PO	P2	T(MAX)	W
8 mm	4.2 mm (.165)	1.5 + 0.1 mm - 0.0 mm (0.59 +.005 000)	1.0 mm (.039)	1.750±.10 mm (.069±.004)	3.5±0.05 mm (.138±.002)	2.4 mm (.094)	4.0±0.1 mm (.157±.00- 4)	4.0±0.1 mm (.157±.00- 4)	2.0±0.05m- m (.079±.002)	0.4 mm (.016)	8.3 mm (.312±.012)

Contact Information

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